To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

Cautions

Keep safety first in your circuit designs!

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   Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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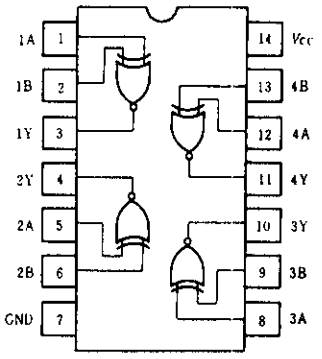
HD74LS266 ●Quadruple 2-input Exclusive-NOR Gates (with open collector outputs)

■PIN ARRANGEMENT



(Top View)

■FUNCTION TABLE

Inputs		Output
A	B	Y
L	L	H
L	H	L
H	L	L
H	H	H

H; high level, L; low level

■RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output voltage	V_{OH}	—	—	5.5	V
Low level output current	I_{OL}	—	—	8	mA

■ELECTRICAL CHARACTERISTICS (Ta=−20~+75℃)

Item	Symbol	Test Conditions		min	typ*	max	Unit
Input voltage	V_{IH}			2.0	—	—	V
	V_{IL}			—	—	0.8	
Output current	I_{OH}	V_{CC}=4.75V, V_{IH}=2V, V_{IL}=0.8V, V_{OH}=5.5V		—	—	100	μA
Output voltage	V_{OL}	V_{CC}=4.75V, V_{IH}=2V, V_{IL}=0.8V	I_{OL}=4mA	—	—	0.4	V
			I_{OL}=8mA	—	—	0.5	
Input current	I_{IH}	V_{CC}=5.25V, V_I=2.7V		—	—	40	μA
	I_{IL}	V_{CC}=5.25V, V_I=0.4V		—	—	−0.8	mA
	I_I	V_{CC}=5.25V, V_I=7V		—	—	0.2	mA
Supply current	I_{CC}**	V_{CC}=5.25V		—	8	13	mA
Input clamp voltage	V_{IK}	V_{CC}=4.75V, I_{IN}=−18mA		—	—	−1.5	V

* V_{CC}=5V, Ta=25°C

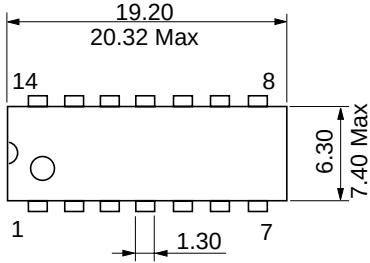
** I_{CC} is measured with one input of each gate at 4.5V, the other inputs grounded, and the outputs open.

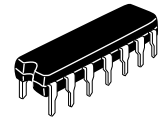
■SWITCHING CHARACTERISTICS (V_{CC}=5V, Ta=25℃)

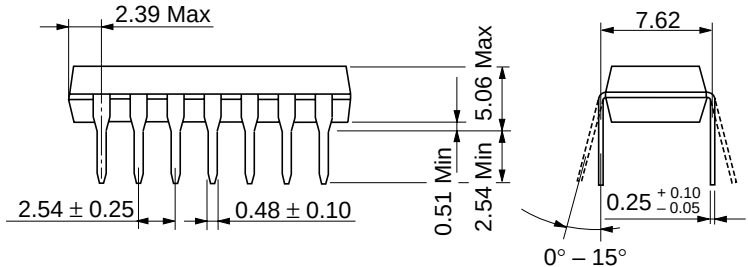
Item	Symbol	Inputs	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PLH}	A or B	C_L=15pF, R_L=2kΩ	—	18	30	ns
	t_{PHL}			—	18	30	
	t_{PLH}	A or B		—	18	30	
	t_{PHL}			—	18	30	

Note) Refer to Test Circuit and Waveform of the Common Item

Unit: mm

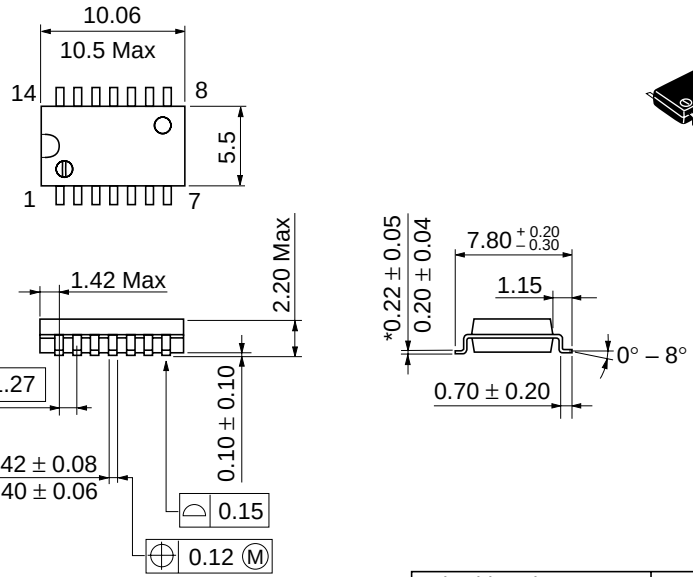


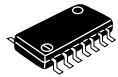




Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.97 g

Unit: mm

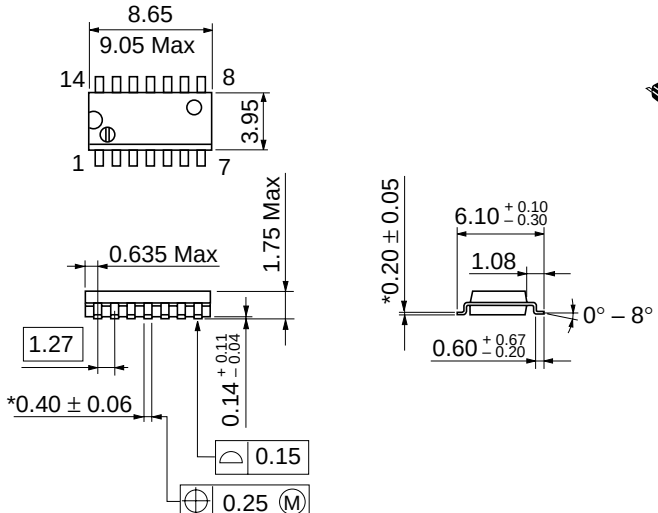




Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Weight (reference value)	0.13 g

*Pd plating

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